

PATENT NUMBER

U.S. UTILITY Patent Application

.I.P.E.

PATENT DATE

SCANNED HKM ⁽³⁾ O.A. q/v

APPLICATION NO. 09/838240	CONT/PRIOR F	CLASS 425	SUBCLASS 116	ART UNIT 1722	EXAMINER Davis
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APPLICANTS

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semi-conductor encapsulation

Resin bonding was done using a multi-plate heating machine

Задание 1

PTO-2040
12/89

ISSUING CLASSIFICATION

[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed. <input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____	_____ (Assistant Examiner) (Date)			NOTICE OF ALLOWANCE MAILED	
	_____ (Primary Examiner) (Date)			ISSUE FEE	
<input type="checkbox"/> The terminal ____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) (Date)			Amount Due	Date Paid
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